



15 April 2007

To: Frank Ruffino, (Chairman EIA CE2.0)
Carl Fritz, (Secretary EIA CE2.0)

From: Jeff Toran, (Deputy Technical Advisor for IEC TC48/SC48B)

RE: IEC Connector standards meetings Fall 2006

Connector and test method related items, TC48 and SC/WGs:

Attendees from the following connector companies – Tyco, Molex, FCI, Harting, Honda, Nexans, Wago, Seimon, Belden, and Reichle de-Massari.

1) Preparation of several new or revised Mod Jack standards continues. As higher data rates are achieved for copper cabling, several connector standards and related test method standards are being prepared to distinguish performance levels consistent with ISO/IEC home and office building telecommunications (including data exchange) standards. The status of these 60603-7 series standards is:

- 60603-7 Ed. 3 – new revision started in 2006 – will be published in late 2007.
- 60603-7-1 Ed. 1 – will be published in 2008.
- 60603-7-3 Ed. 1 - will be published in late 2007
- 60603-7-4 Ed. 1 – published in 2006.
- 60603-7-5 Ed. 1 - will be published in late 2007
- 60603-7-7 Ed. 1 – published in 2005.
- 60603-7-41 Ed. 1 – variant of 60603-7-4, new standard, will be published in 2008.
- 60603-7-51 Ed. 1 – variant of 60603-7-4, new standard, will be published in 2008.
- 60603-7-71 Ed. 1 – variant of 60603-7-4, new standard, will be published in 2008.

- Also, 61076-3-110 Ed. 1 which is a variant of 60603-7-7 will be published in late 2007 or early 2008.

Two new 60512 standards for high speed signal measurements for the 60603-7-4, -5 and -7 connectors are being prepared. These will be published late in 2008.

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- 2) Six industrial Ethernet standards are being prepared to standardize on some common protective housing geometries for the Mod Jack connector when used in industrial environments. These will be published late in 2007.
- 3) Two circular connector standards are being prepared to support the PROFIBUS protocol for industrial equipment communications/data exchange. A third standard was published in 2006.
- 4) The Small Form Factor (SFF) group is leading a project team to publish IEC standard versions of their SCA-2 and HSSDC-2 connectors and related measurement publications.
- 5) The ISO/IEC/JTC1/SC25 committee (telecomm cabling committee referenced in (1) above) has requested sC48B to prepare a report regarding a 'hot' mating/unmating test for Power over Ethernet applications. There is a good deal of concern about erosion of the contact surfaces from "hot" mating/unmating. Mr. Yakov Belopolsky (Bell-Stewart Connectors) and Mr. Matthias Gerber (Reichle de-Massari Connectors) coordinated testing to evaluate the degree of erosion that occurs at the voltages requested by the ISO/IEC committee. The report they prepared will be published as an IEC Technical Report later in 2007.
- 6) A new 60352 series (Solderless terminations) standard is being drafted for compression connectors. It was initiated by Japan.

The next scheduled meetings are for the three Working Groups in May 2007.